

IN THE CLAIMS

Please amend the claims as follows.

sub
C1
E1

- 1 14. (Twice Amended) An apparatus comprising:
2 a first substrate with a semiconductor film formed thereon;
3 wherein said semiconductor film is demarcated from a rest of said first
4 substrate by a damaged surface, with the damaged surface being removed; and
5 a second substrate with a metal film formed thereon, said second substrate
6 bonded with the metal film to said semiconductor film of said first substrate].

C2

- 1 17. (Amended) The apparatus of claim [14] 24 wherein said metal film includes a
2 noble metal.

C3

- 1 19. (Amended) The apparatus of claim [14] 24 wherein said metal film is formed
2 on a second film of oxide formed on said second substrate.

C4

- 1 20. (Twice Amended) An apparatus comprising:
2 a substrate;
3 a first oxide film formed on said substrate;
4 a metal film formed on said first oxide film;
5 the first oxide film debonds the metal film from the substrate;
6 a second oxide layer formed on said metal film; [and]
7 a semiconductor film formed on said second oxide film, said semiconductor
8 film having [a least one active device formed therein] a first level of